DATA SHEET

SMP1345 Series: Very Low Capacitance, Plastic Packaged Silicon PIN Diodes

Applications
- High isolation LNBs, WLANs, and wireless switches

Features
- Very low insertion loss: 0.4 dB
- Capacitance: 0.15 pF
- Packages rated MSL1, 260 °C per JEDEC J-STD-020

Skyworks Green™ products are compliant with all applicable legislation and are halogen-free. For additional information, refer to Skyworks Definition of Green™, document number SQ04–0074.

Description
The SMP1345 series of plastic packaged, surface mountable PIN diodes is designed for high volume Low-Noise Block (LNB), Wireless Local Area Network (WLAN), and switch applications from 10 MHz to 6 GHz. The short carrier lifetime of 100 ns (typical), combined with their thin I-region width of 10 μm (nominal) results in a group of fast speed RF switching PIN diodes.

The RF performance of the SMP1345 series is assured by virtue of their very low capacitance (0.15 pF) and low resistance (1.5 Ω at 10 mA).

Table 1 describes the various packages and marking of the SMP1345 series.

<table>
<thead>
<tr>
<th>Table 1. SMP1345 Series Packaging and Marking</th>
</tr>
</thead>
<tbody>
<tr>
<td><img src="image1" alt="Image" /></td>
</tr>
<tr>
<td>Common Cathode</td>
</tr>
<tr>
<td>SOT-23</td>
</tr>
<tr>
<td>SMP1345-004LF Green™</td>
</tr>
<tr>
<td>Ls = 1.5 nH</td>
</tr>
</tbody>
</table>
Electrical and Mechanical Specifications

The absolute maximum ratings of the SMP1345 series are provided in Table 2. Electrical specifications are provided in Table 3.

Table 2. SMP1345 Series Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Minimum</th>
<th>Maximum</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse voltage Vr</td>
<td></td>
<td>50</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Power dissipation @ 25 °C lead temperature Ps</td>
<td></td>
<td>250</td>
<td></td>
<td>mW</td>
</tr>
<tr>
<td>Storage temperature TSTG</td>
<td></td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
</tr>
<tr>
<td>Operating temperature TA</td>
<td></td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
</tr>
<tr>
<td>Electrostatic discharge:</td>
<td></td>
<td>ESD</td>
<td>1000</td>
<td>V</td>
</tr>
</tbody>
</table>

1 Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

ESD HANDLING: Although this device is designed to be as robust as possible, electrostatic discharge (ESD) can damage this device. This device must be protected at all times from ESD when handling or transporting. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD handling precautions should be used at all times.

Table 3. SMP1345 Series Electrical Specifications

(TA = +25 °C, Unless Otherwise Noted)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reverse current Ir</td>
<td>ln</td>
<td>Vr = 50 V</td>
<td>10</td>
<td></td>
<td></td>
<td>µA</td>
</tr>
<tr>
<td>Capacitance C</td>
<td>CT</td>
<td>F = 1 MHz: V = 1 V</td>
<td>0.19</td>
<td>0.18</td>
<td>0.20</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V = 5 V</td>
<td></td>
<td></td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Resistance Rs</td>
<td>RS</td>
<td>F = 100 MHz:</td>
<td>3.5</td>
<td>1.5</td>
<td>2.0</td>
<td>Ω</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I = 1 mA</td>
<td></td>
<td></td>
<td></td>
<td>Ω</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I = 10 mA</td>
<td></td>
<td></td>
<td></td>
<td>Ω</td>
</tr>
<tr>
<td>Forward voltage Vf</td>
<td></td>
<td>Ir = 10 mA</td>
<td>0.89</td>
<td></td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Carrier lifetime T</td>
<td>TI</td>
<td>Ir = 10 mA</td>
<td>100</td>
<td></td>
<td></td>
<td>ns</td>
</tr>
<tr>
<td>I region width</td>
<td></td>
<td></td>
<td>10</td>
<td></td>
<td></td>
<td>µm</td>
</tr>
</tbody>
</table>

1 Performance is guaranteed only under the conditions listed in this table.
Typical Performance Characteristics

Figure 1. Total Capacitance vs Reverse Voltage

Figure 2. Series Resistance vs Current @ 100 MHz

Figure 3. Forward Current vs Forward Voltage

Figure 4. Insertion Loss vs Frequency (Ir = 10 mA)

Figure 5. Isolation vs Frequency (Vn = 0 V)

Figure 6. Return Loss vs Frequency (Ir = 10 mA)
Package Dimensions
Package dimensions are shown in Figures 7 to 11 (odd numbers), and tape and reel dimensions are provided in Figures 8 to 12 (even numbers).

Package and Handling Information
Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

The SMP1345 series is rated to Moisture Sensitivity Level 1 (MSL1) at 260 °C. It can be used for lead or lead-free soldering. For additional information, refer to the Skyworks Application Note, Solder Reflow Information, document number 200164. Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format.
**Notes:**

1. Carrier tape: black conductive polycarbonate or polystyrene.
2. Cover tape material: transparent conductive PSA.
3. Cover tape size: 5.4 mm width.
4. ESD-surface resistivity is ≤1 x 10^8 Ohms/square per EIA, JEDEC TNR Specification.
5. All measurements are in millimeters.

**Figure 7. SC-79 Package Dimension Drawing**

**Figure 8. SC-79 Tape and Reel Dimensions**
Figure 9. SOT-23 Package Dimension Drawing

Figure 10. SOT-23 Tape and Reel Dimensions

Notes:
1. Carrier tape: black conductive polycarbonate.
2. Cover tape material: transparent conductive PSA.
3. Cover tape size: 5.40 mm width.
4. Tolerance = ±0.10 mm.
5. Ten sprocket hole pitch cumulative tolerance: ±0.2 mm.
6. All measurements are in millimeters.
7. Alternative carrier tape dimensions are:
   - \( A_0 = 3.3 \)
   - \( B_0 = 2.9 \)
   - \( K_0 = 1.22 \)
Notes:

1. All measurements are in millimeters.
3. These packages are used principally for discrete devices.
4. This dimension includes stand-off height and package body thickness, but does not include attached features, e.g., external heatsink or chip capacitors. An integral heatslug is not considered an attached feature.
5. This dimension is primarily terminal plating, but does not include small metal protrusion.

Figure 11. SOD-882 Package Dimension Drawing

Notes:

1. Carrier tape: black conductive polycarbonate.
2. Cover tape: transparent conductive material.
3. Cover tape size: 5.4 mm width.
4. ESD surface resistivity is $1 \times 10^4 \leq \sigma \leq 1 \times 10^8$ Ohms/square.
5. All dimensions are in millimeters.

Figure 12. SOD-882 Tape and Reel Drawing